

ASIC Development - System Aspects

Power Distribution

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Terascale Detector Workshop - Heidelberg

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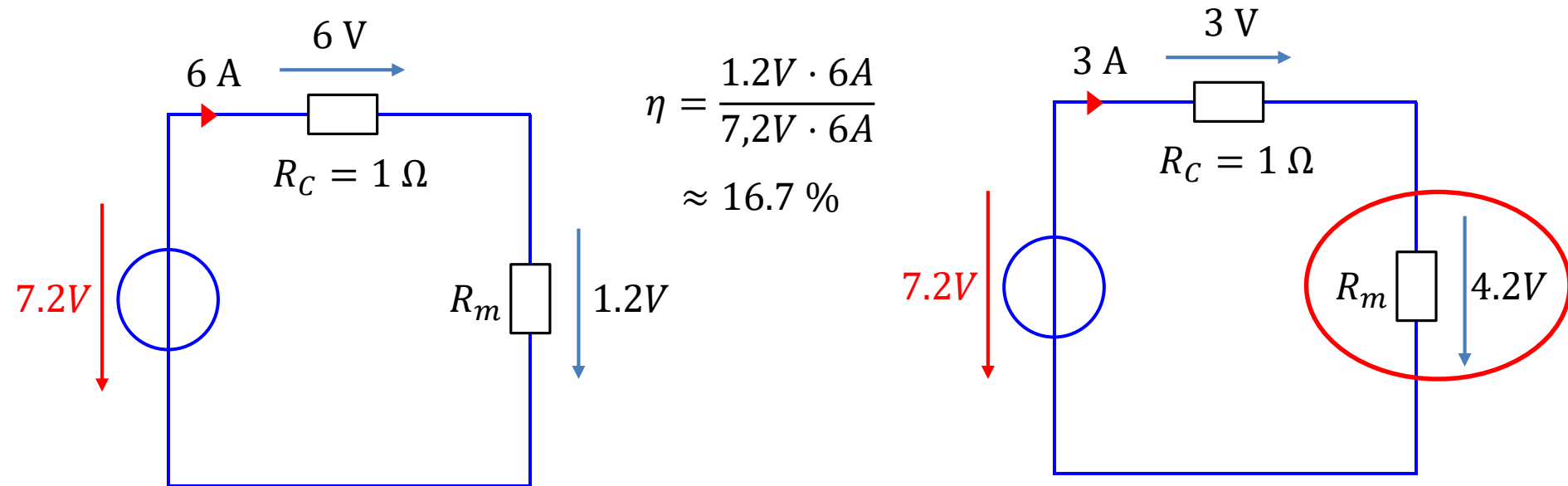
- Hybrid-Pixel detectors are power hungry devices

Chip	Pixel Area	Current per Pixel	Current Density
FE-I3	50 x 400 μm^2	47 μA	1400 A/m^2
FE-I4	50 x 250 μm^2	16 μA	1280 A/m^2
RD53	50 x 50 μm^2	7 μA	2800 A/m^2

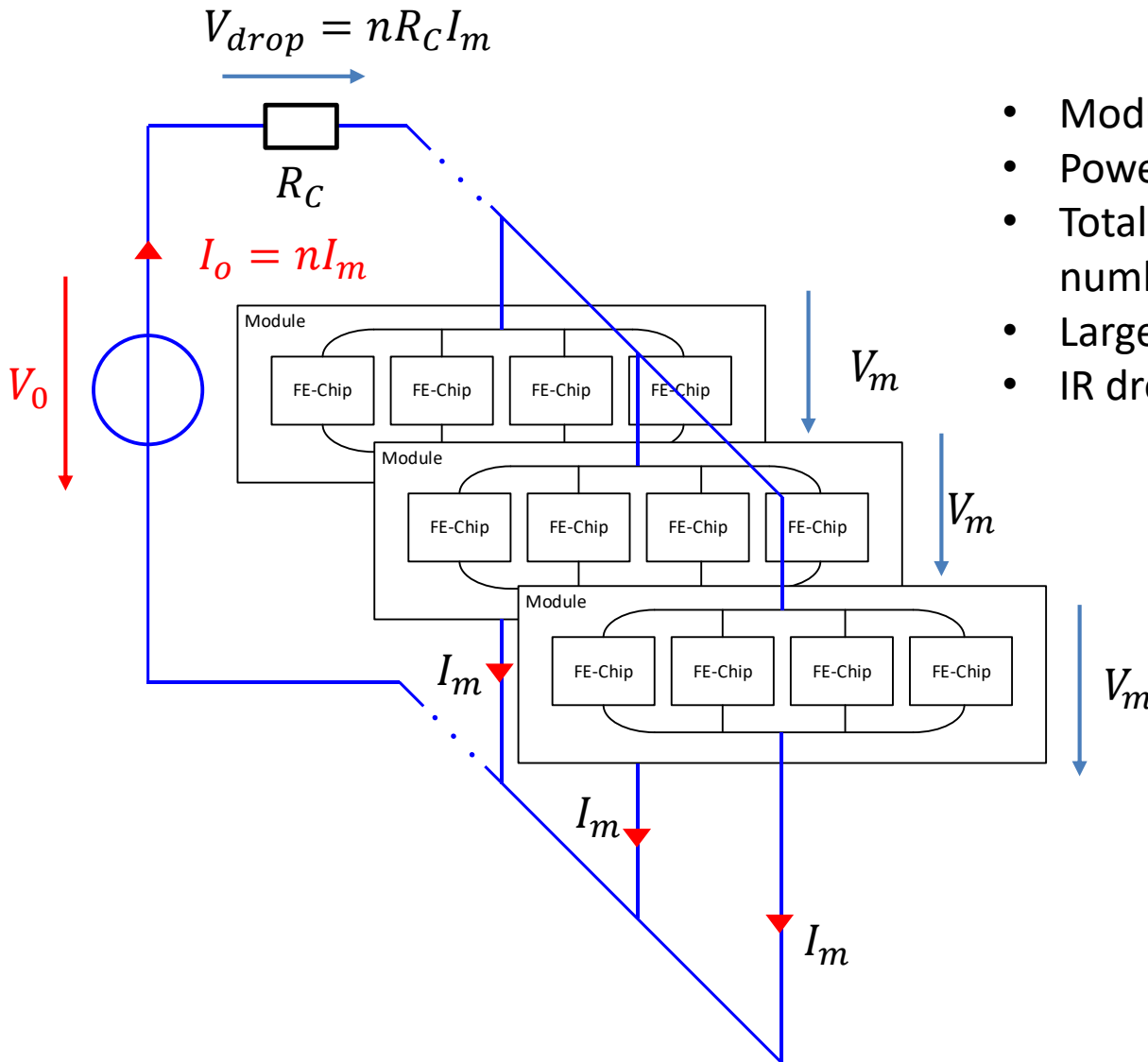
- Increased current consumption caused by
 - parasitic detector capacitances
 - additional digital functionality
- ITkPix quad-module expected to consume 4.5-7.5 A of current
 - Exact current consumption depends module position e.g. layer

Need for Low Mass

- detector mass influences the tracking and calorimeter resolution
 - multiple-scattering, Bremsstrahlung, photon conversion
- limited material budget
 - affects available number and diameter of supply lines
 - no sense lines
- long supply lines
 - power supplies are outside the active area
 - assuming c.a. 200m aluminum of 5 mm² diameter gives 1Ω cable resistance



Power Efficiency of Conventional Power Scheme



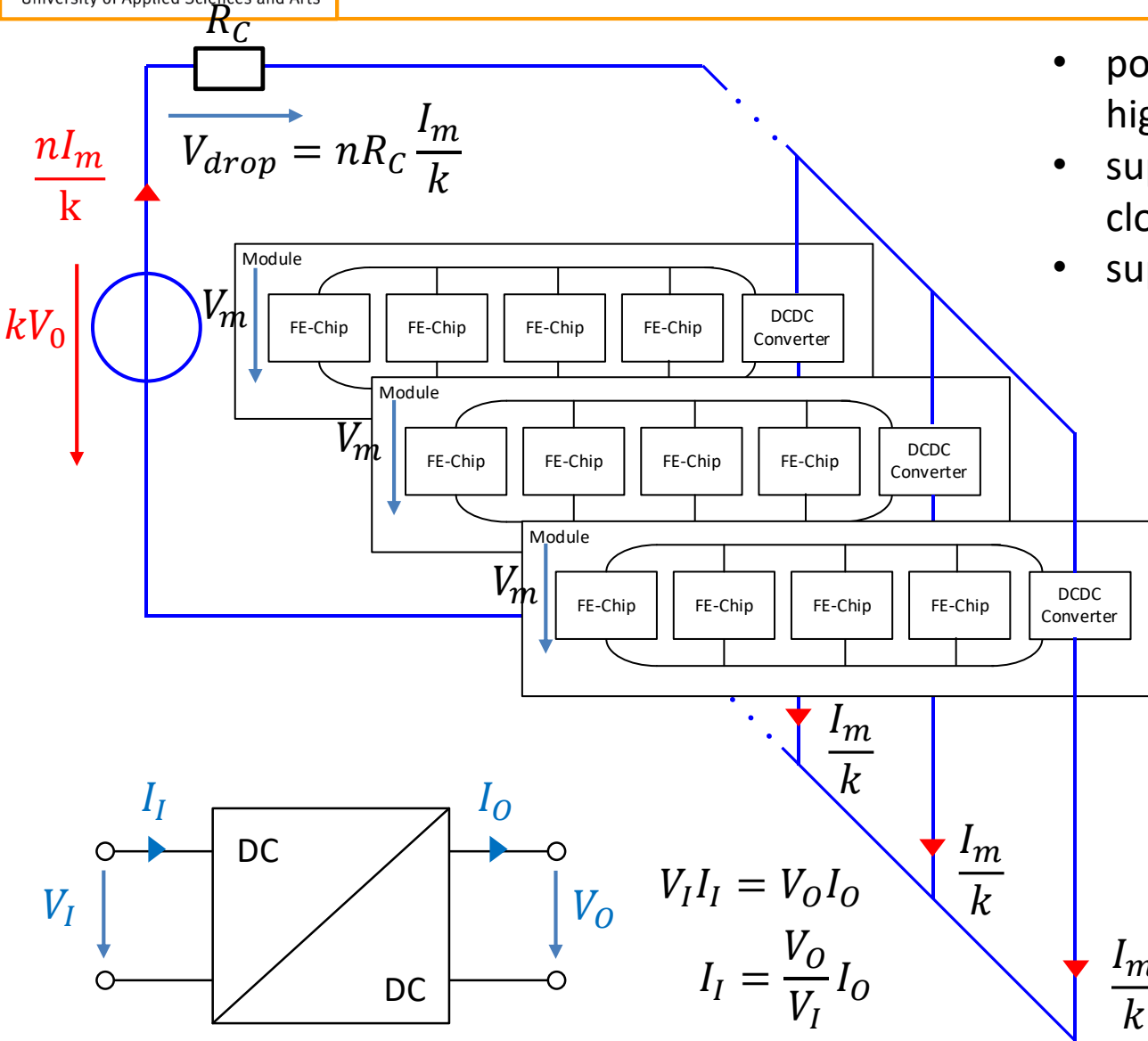
- Modules are connected in parallel
- Powered by constant voltage source
- Total supply current scales with the number n of modules
- Large supply currents affect efficiency
- IR drops on power cables

$$\eta = \frac{1}{1 + n \frac{R_C I_m}{V_m}}$$

$$\eta = \frac{1}{1 + 16 \frac{1\Omega \cdot 6A}{1,2V}}$$

$$\approx 1.23 \%$$

DC / DC Conversion



- power is distributed at k-times higher supply voltage
- supply voltage is converted down close to the load
- supply current is reduced by k

$$\eta = \frac{1}{1 + \frac{n R_C I_m}{k^2 V_m}}$$

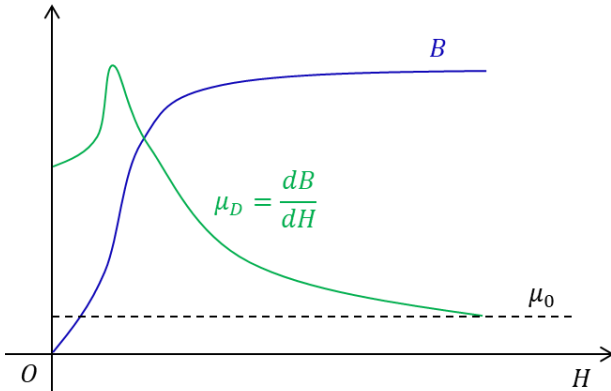
$$\eta_4 = \frac{1}{1 + \frac{16 \cdot 1\Omega \cdot 6A}{16 \cdot 1.2V}}$$

$$\approx 16.7 \%$$

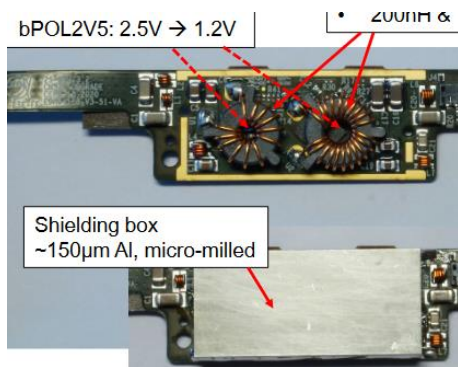
$$\eta_8 \approx 44.4 \%$$

$$\eta_{16} \approx 76.2 \%$$

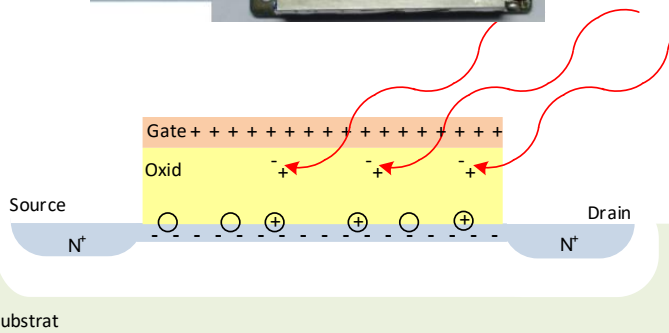
Special Conditions in HEP Experiments



- High magnetic field to measure momenta and charge
- ferromagnetic materials saturate
- only air coils applicable
- air coils have larger dimensions than coils with core

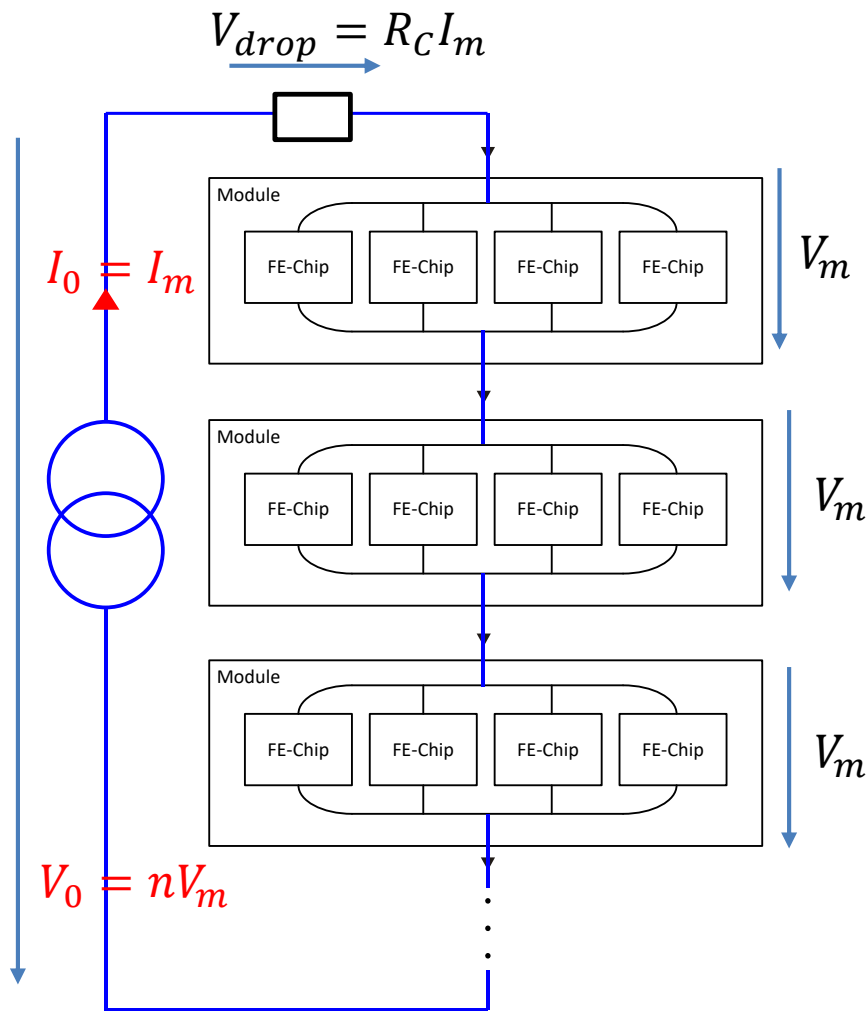


- frontend electronics very sensitive to noise coupling
- shielding of coil required
- increased material budget



- higher voltages can only be handled by thick-gate oxide transistors
- significant radiation induced threshold voltage shifts for gate-oxide thickness larger than 5nm

Serial Powering



- modules are connected in series
- powered by constant current source
- total supply current is defined by maximum load current of a single module
- total supply voltage across the chain scales with the number of powered modules

$$\eta = \frac{1}{1 + \frac{R_C I_m}{n V_m}}$$

- regulator circuitry required to generate constant supply voltage out of constant current

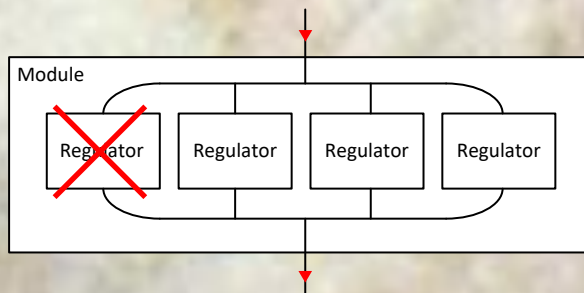
$$\eta = \frac{1}{1 + \frac{1\Omega \cdot 6A}{16 \cdot 1.2V}}$$

$$\approx \frac{1}{1 + \frac{1\Omega \cdot 6A}{16 \cdot 1.2V}}$$

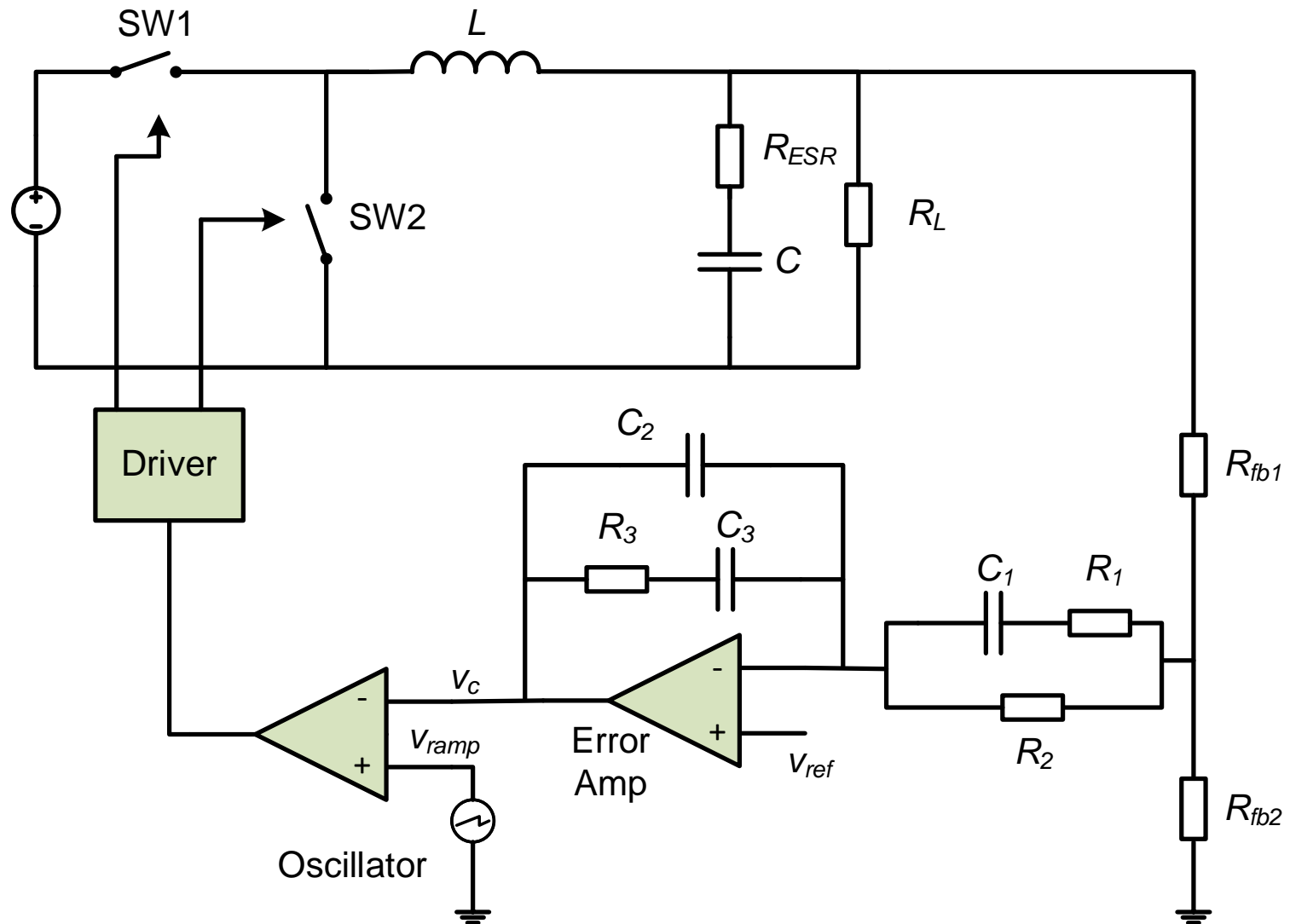
$$\approx 76,2\%$$

The Serial Powering Commandments

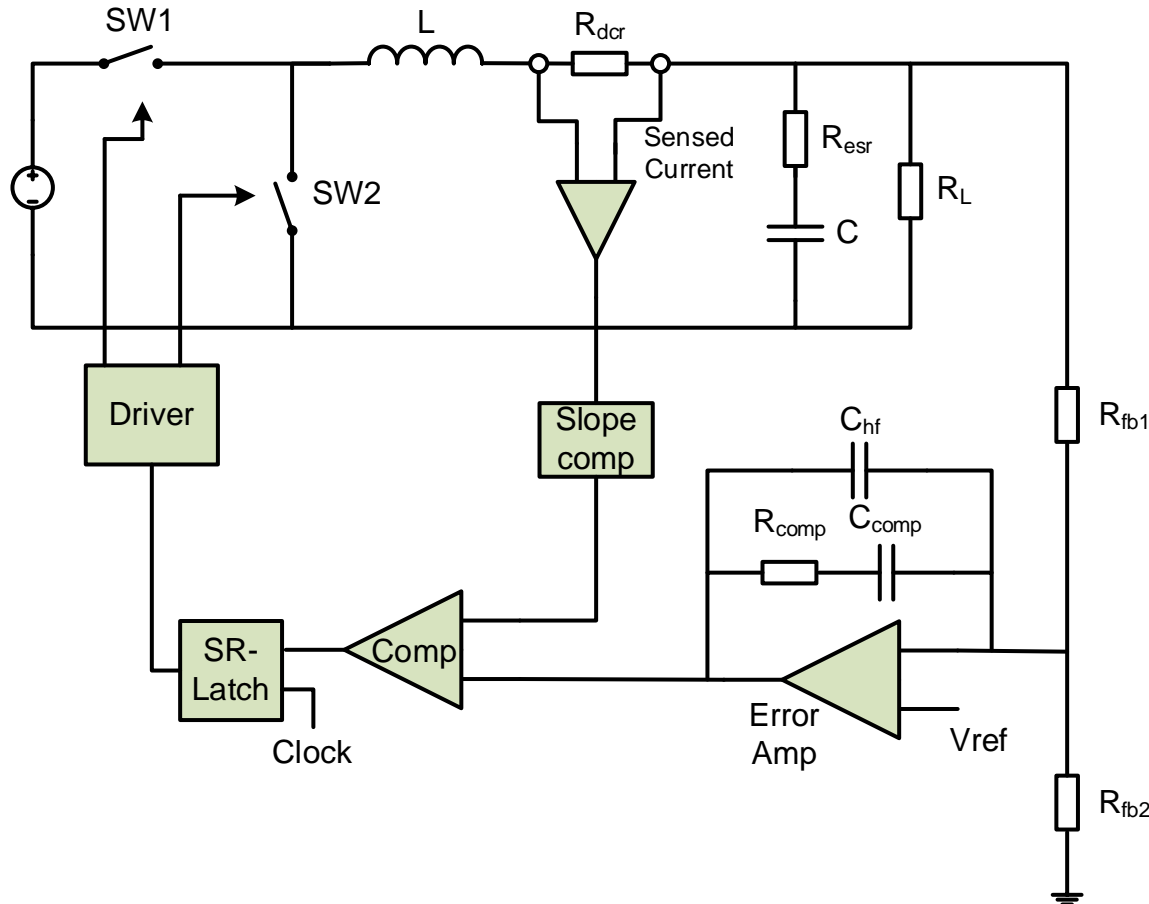
- You shall prevent the break of the serial powering chain
- You shall avoid hot spots
- You shall distribute power equally across the chips and the module
- You shall avoid single point of failure
- You shall introduce redundancy
- You shall operate several regulators in **parallel** on module level



Voltage Controlled Buck Converter



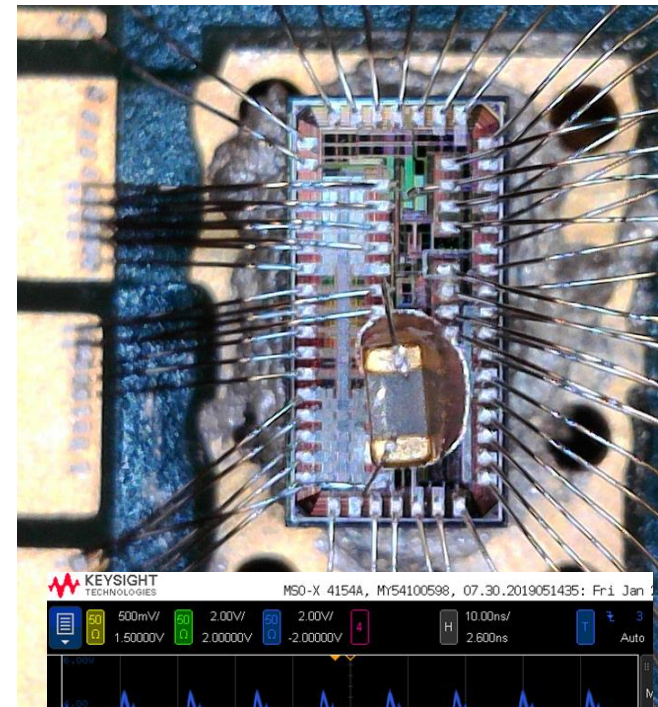
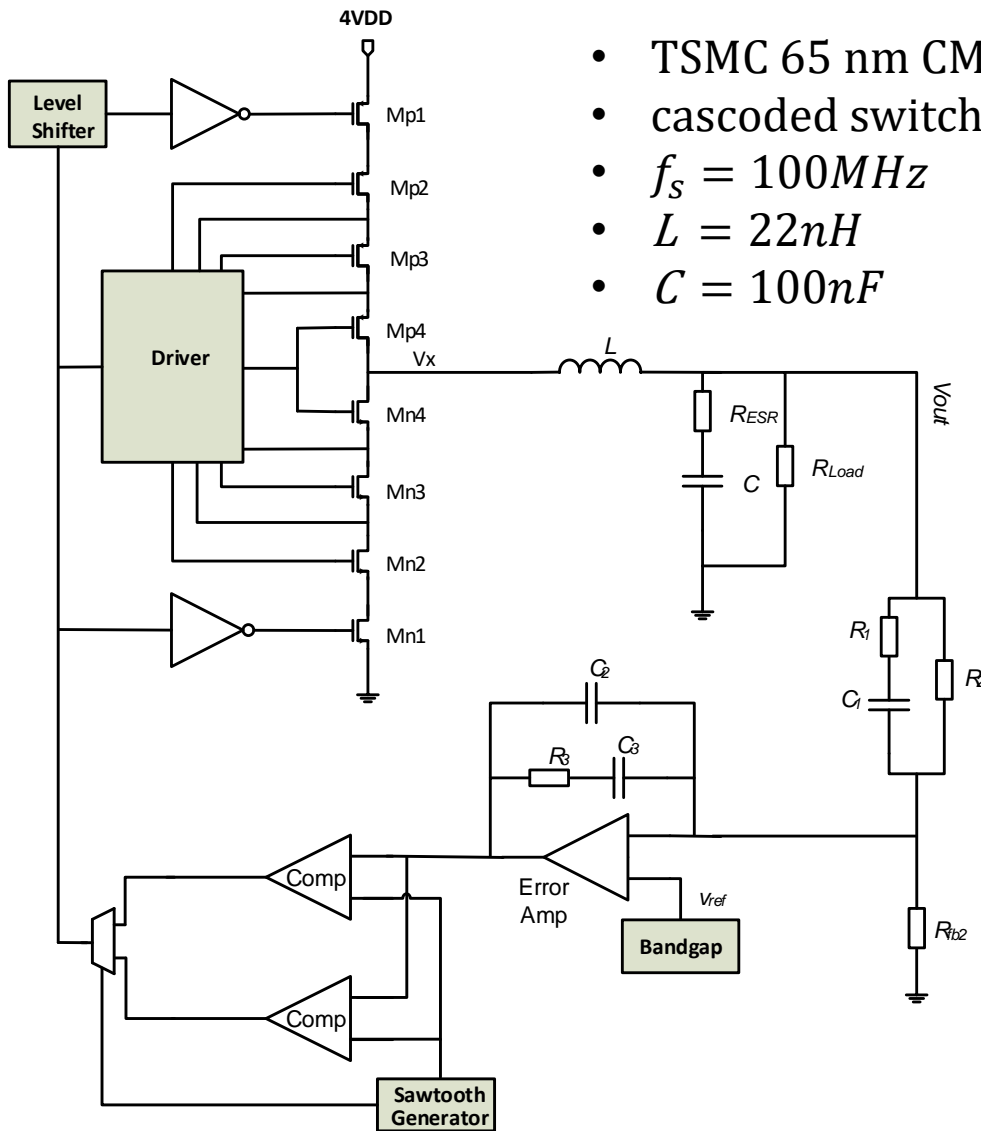
Current Controlled Buck Converter



- inductance current is controlled
- If inductance current reaches peak value SW1 is opened
- output voltage determines peak value
- inductor behaves like a current source
- regulation loop becomes single pole system
- much easier to compensate

High-Frequency Buck-Converter

- TSMC 65 nm CMOS
- cascoded switching stage
- $f_s = 100\text{MHz}$
- $L = 22\text{nH}$
- $C = 100\text{nF}$

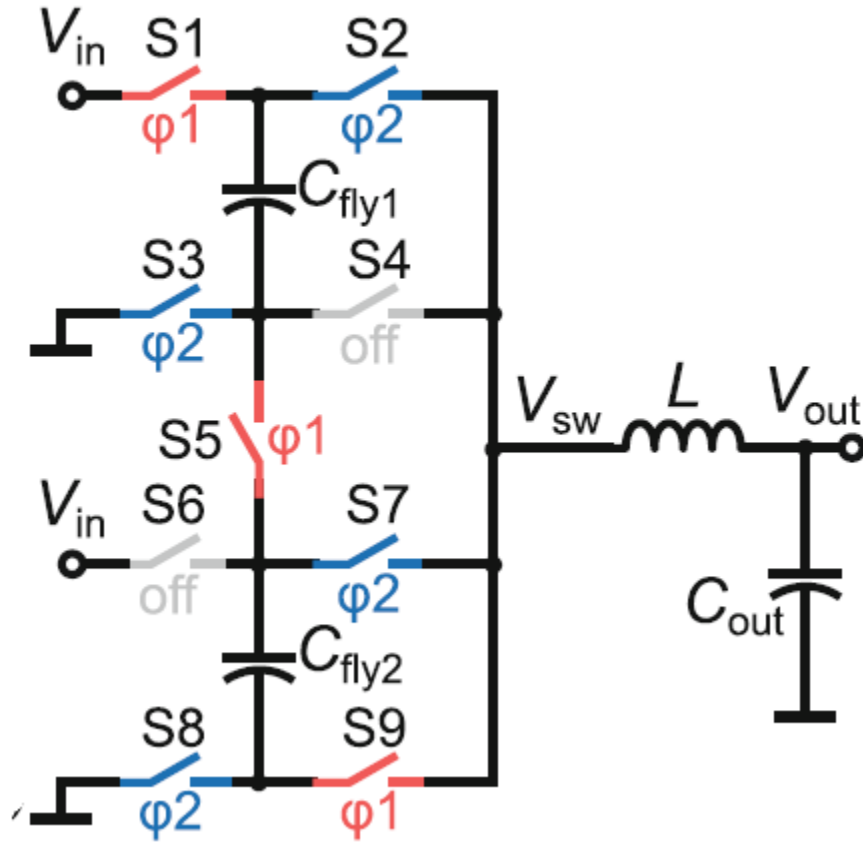


Vx

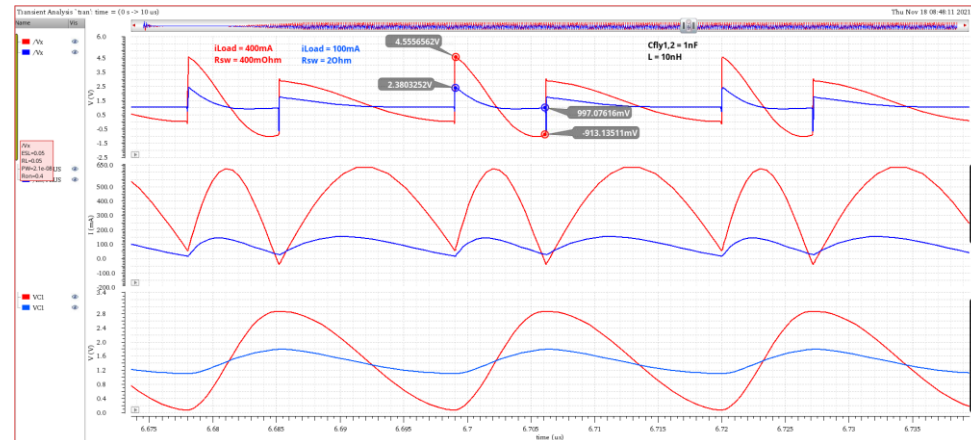
PWM

Oscillator

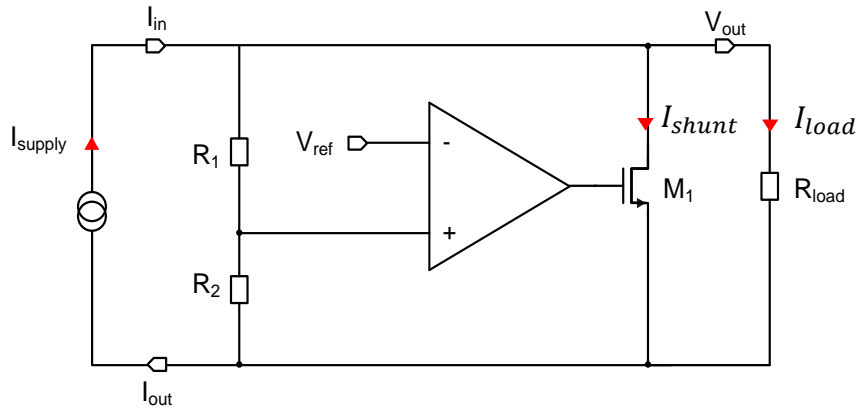
3-1 Resonant Converter



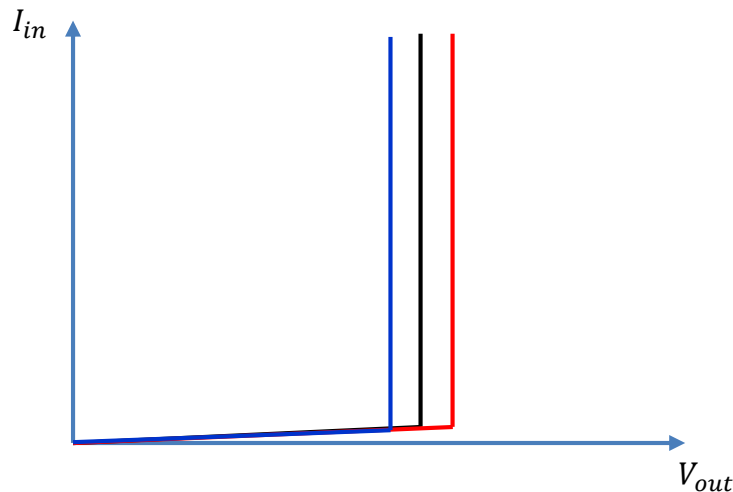
- Converter Is operated at higher frequencies close to resonant frequency
- Passive components can be reduced in size significantly
- Switching occurs when current becomes zero
 - Higherer efficiency



Shunt Regulator Operation Principle



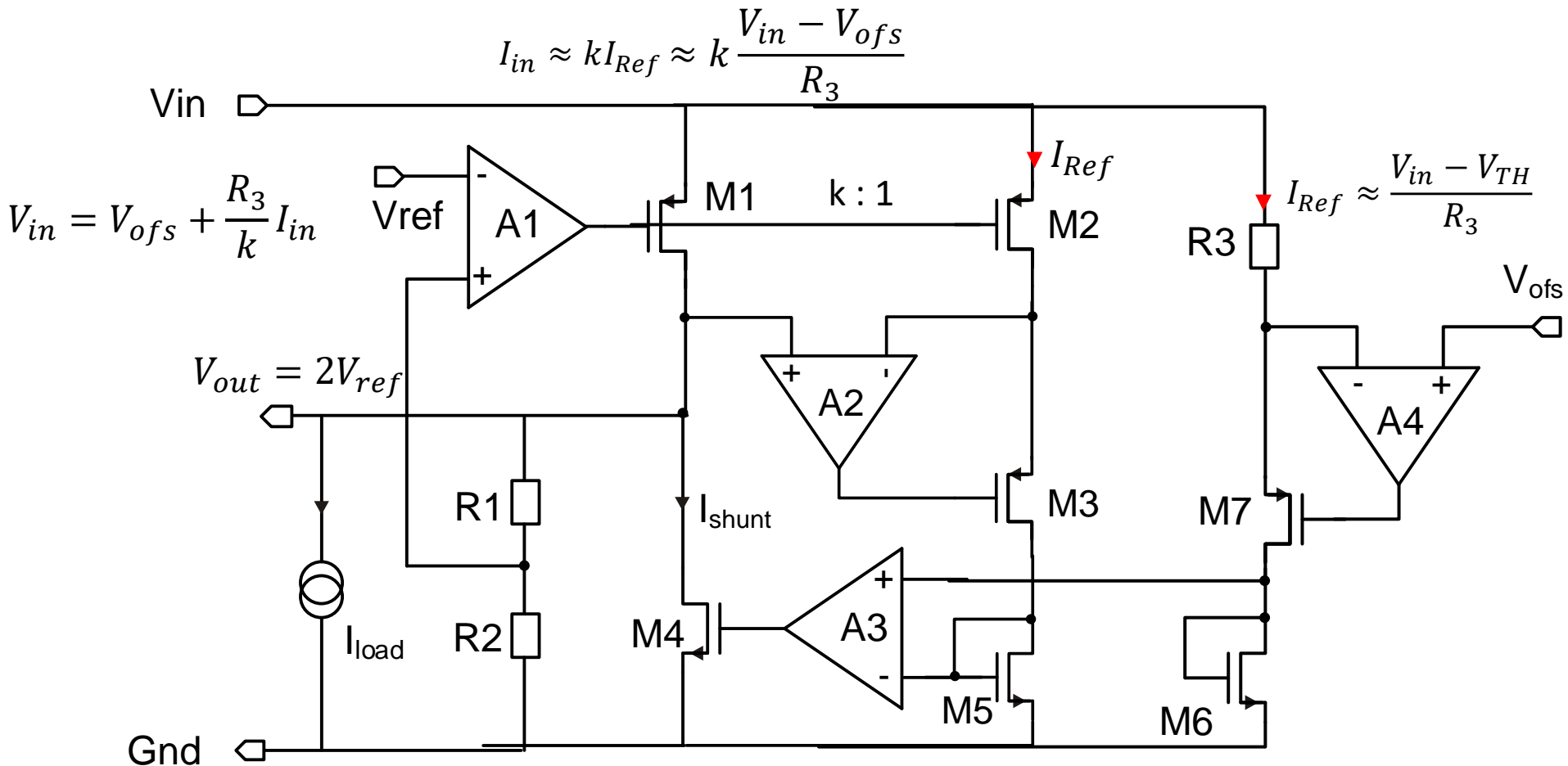
- Voltage regulation by current steering
- Current flow through load defines V_{out}
- Referenced voltage $V_{out} = \left(1 + \frac{R_1}{R_2}\right) V_{ref}$
- Excess current I_{Shunt} is shunted by M1
- $I_{in} > I_{load} \rightarrow \eta = \frac{I_{load}}{I_{in}}$



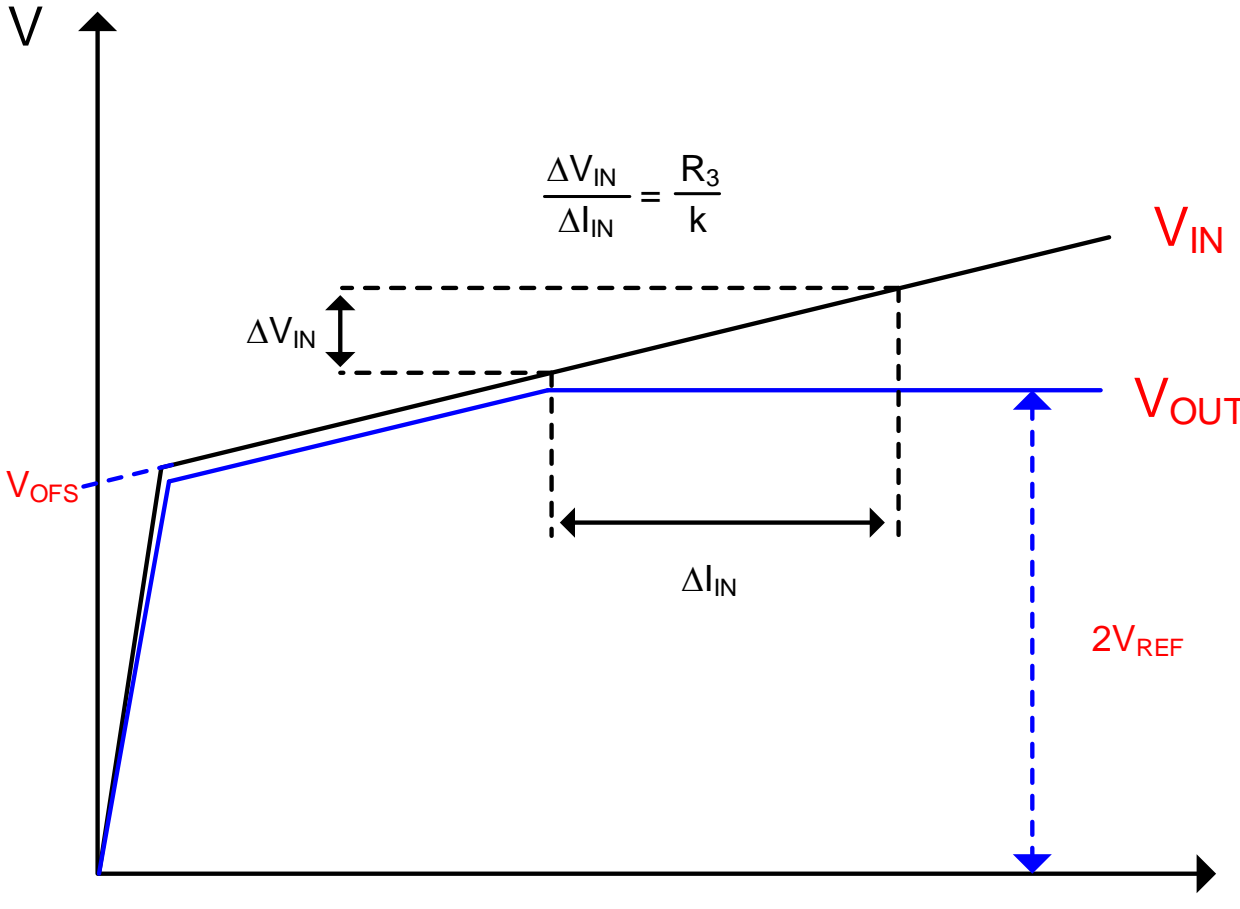
- Very steep voltage to current characteristic
- → Small voltage source output impedance 😊
- → Unbalanced current distribution across parallel placed regulators 😞
- Parallel placed regulators generate different V_{out}
 - voltage reference variations
 - error amplifier offset
 - resistor mismatch
 - ground shifts
- Current will flow through regulator with small V_{out}
- Regulator may be destroyed due to overload cond.

Design Concept

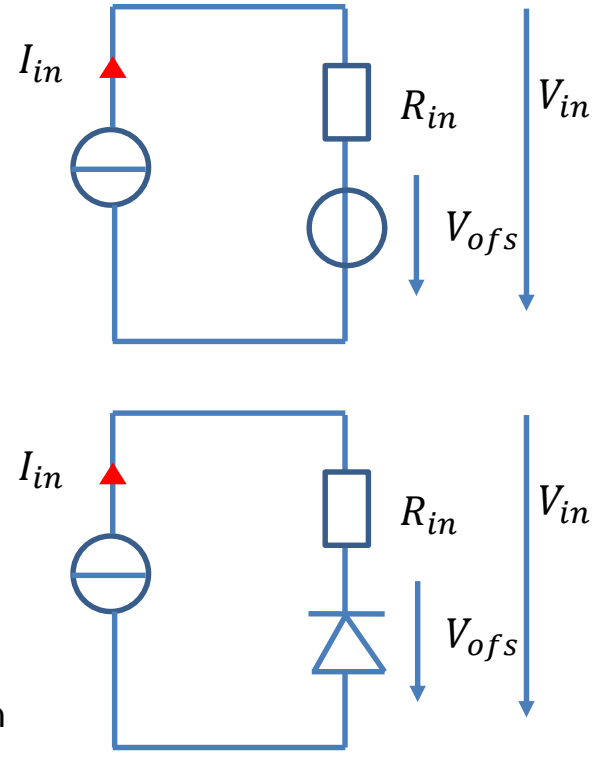
- The Shunt-LDO regulator combines the functionality of an LDO voltage regulator with the capability of a shunt regulator to drain a constant current
- Two control loops: 1) constant output voltage 2) constant current flow through the regulator



V/I Characteristic



$$V_{in} = V_{ofs} + \frac{R_3}{k} I_{in}$$



Conclusion

- Power Aspects are always relevant and challenging
 - Especially due to additional constraints in HEP experiments
- Conventional parallel/voltage based powering scheme is not viable
 - Radiation hard custom made DC/DC converters are an option for outer layers
 - Serial Powering with SLDO are used in inner layers
- Hybrid/Resonant Converters may allow DC/DC conversion in hybrid-pixel detectors
 - e.g. as an alternative to short serial chains with 3D sensors